

**Data Sheet 1324 Rev.A**

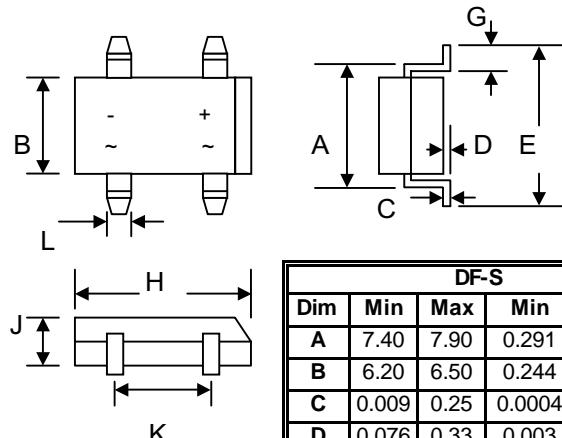
**Features**

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material – UL Recognition Flammability Classification 94V-O
- UL Recognized File # E223064

**Mechanical Data**

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.38 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

\*Low profile models (J = 2.20~2.50mm) are available.  
Please consult factory.



DF-S				
Dim	Min	Max	Min	Max
A	7.40	7.90	0.291	0.311
B	6.20	6.50	0.244	0.256
C	0.009	0.25	0.0004	0.001
D	0.076	0.33	0.003	0.013
E	—	10.40	—	0.409
G	1.02	1.53	0.040	0.060
H	8.13	8.51	0.320	0.321
J*	3.20	3.40	0.126	0.134
K	5.0	5.20	0.197	0.205
L	1.0	1.20	0.039	0.047
		In mm	In inch	

**Maximum Ratings and Electrical Characteristics** @ $T_A=25^\circ\text{C}$  unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	DF 005S	DF 01S	DF 02S	DF 04S	DF 06S	DF 08S	DF 10S	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>								
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_A = 40^\circ\text{C}$	I <sub>O</sub>					1.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>					30			A
Forward Voltage per element @ $I_F = 1.0\text{A}$	V <sub>FM</sub>					1.1			V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I <sub>RM</sub>					10			$\mu\text{A}$
						500			
Typical Junction Capacitance per element (Note 1)	C <sub>J</sub>					25			pF
Typical Thermal Resistance (Note 2)	R <sub>θJA</sub>					110			K/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>					-65 to +150			°C

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

2. Thermal resistance junction to ambient mounted on PC board with 5.0mm<sup>2</sup> (0.03mm thick) land areas.

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